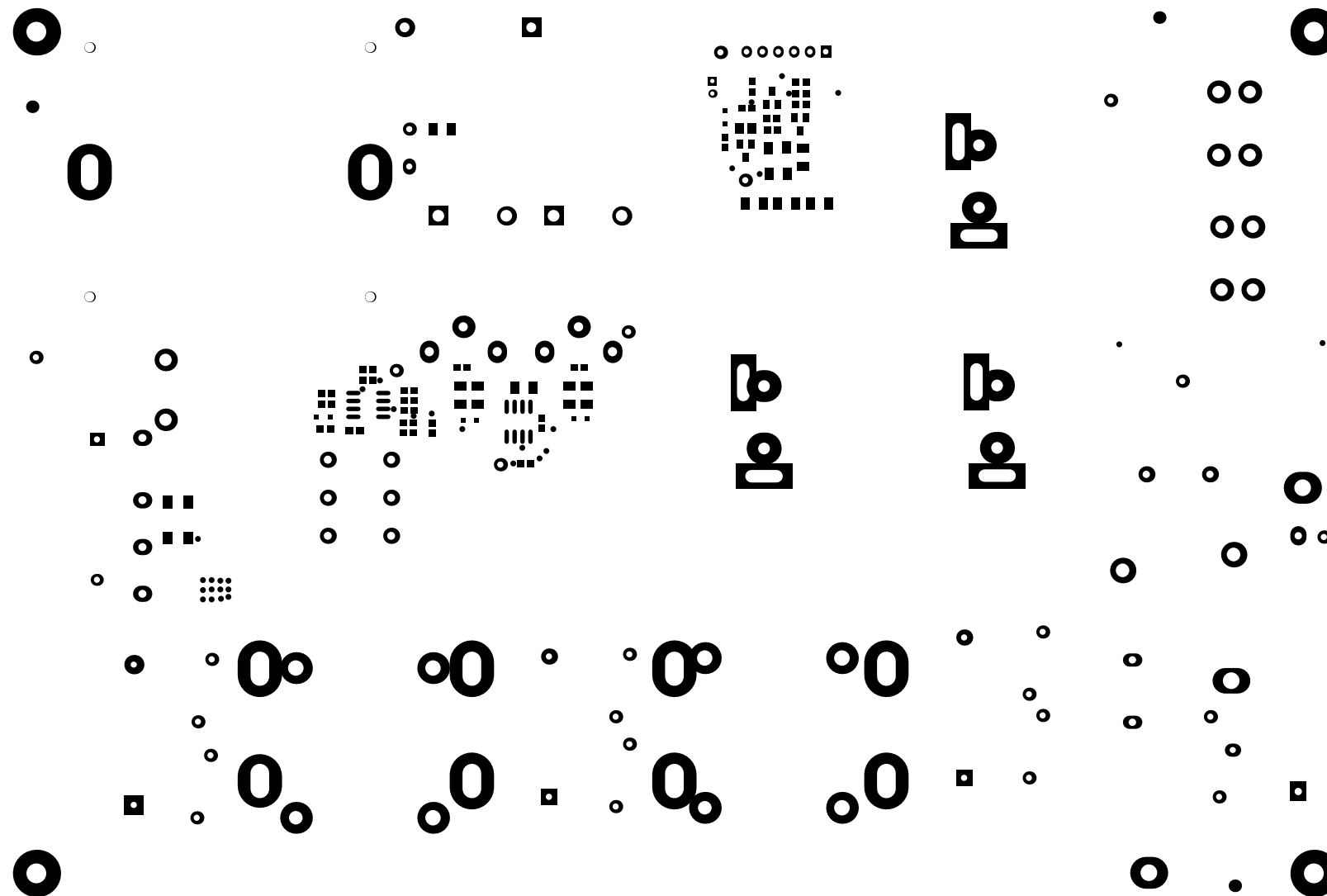
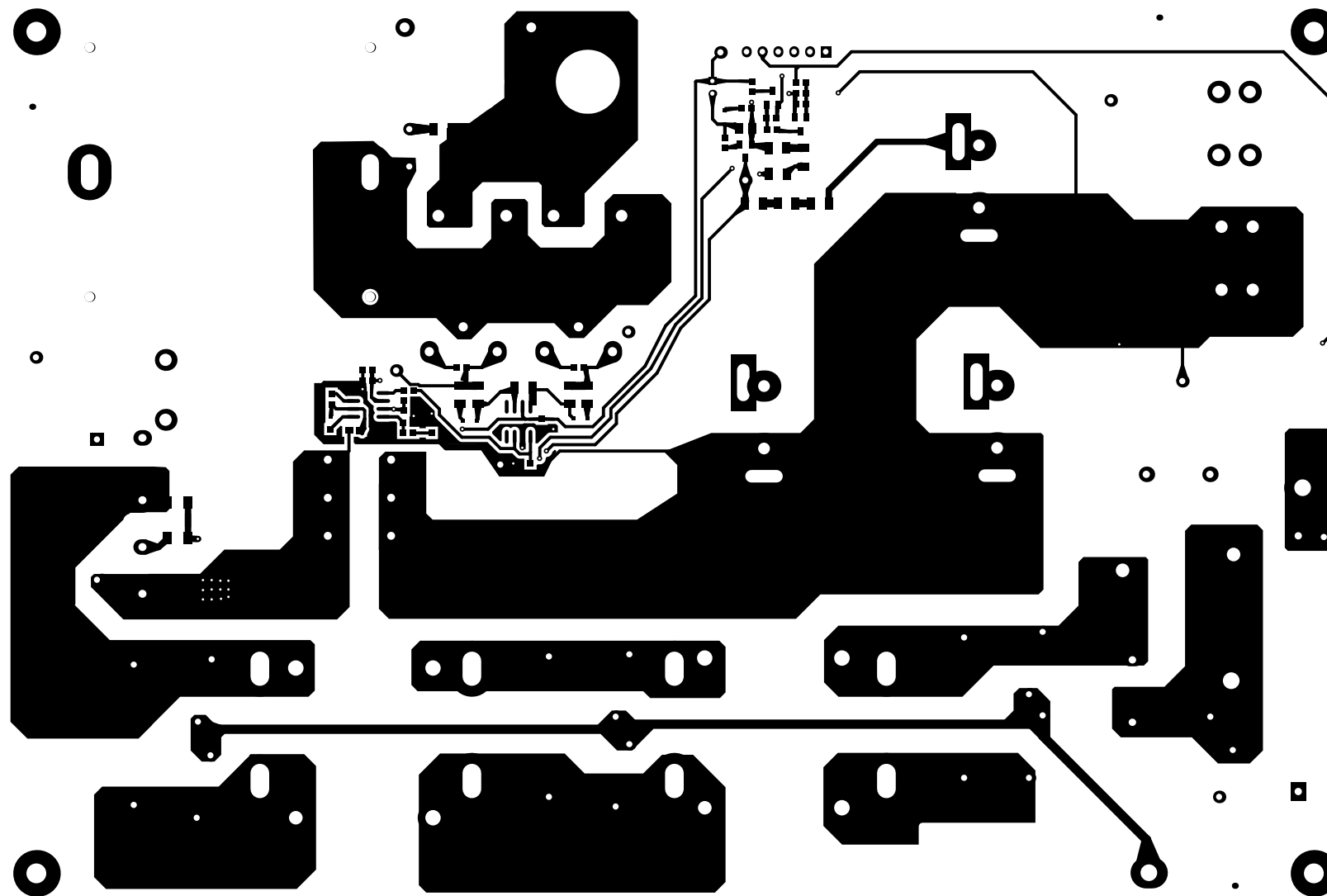


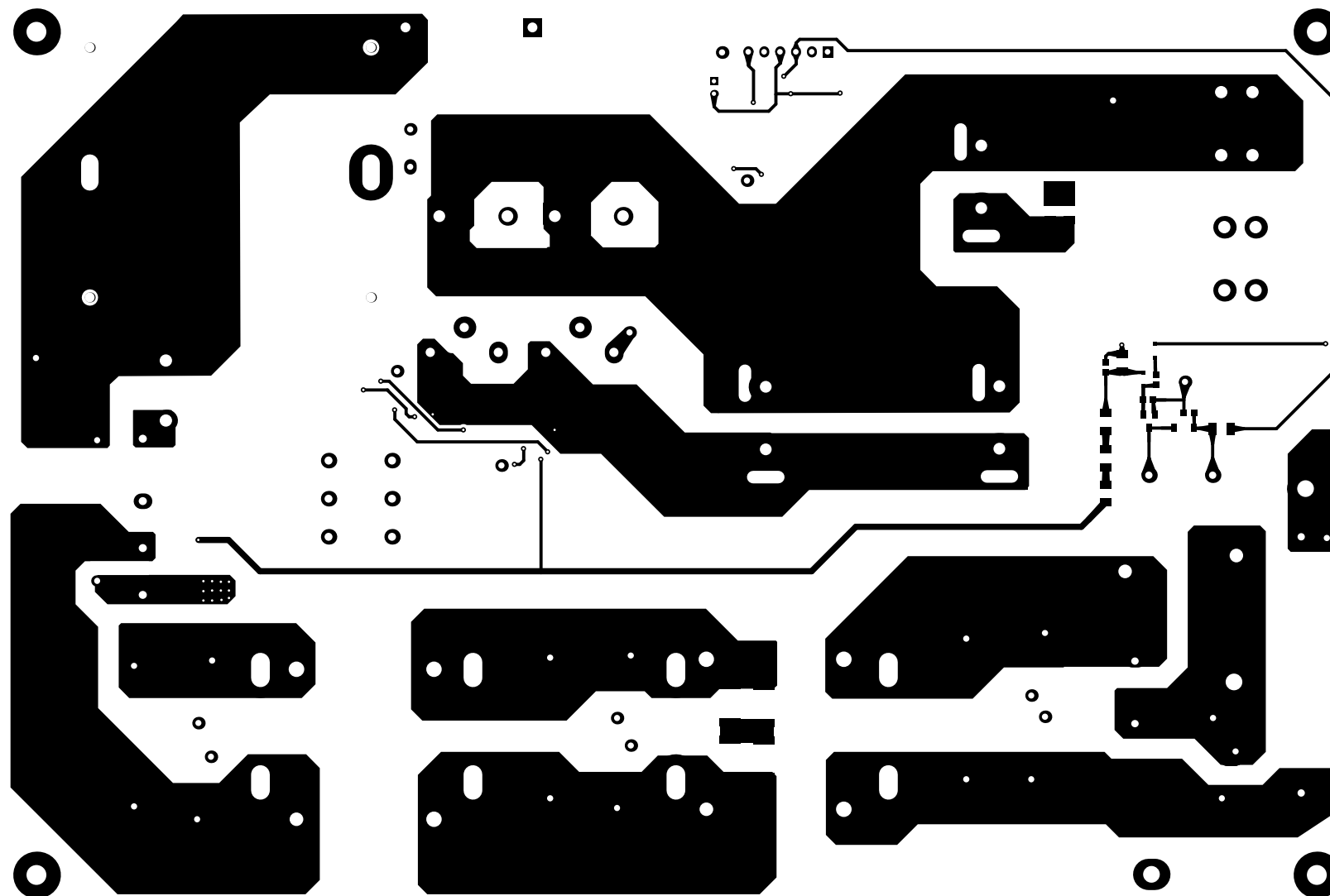
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Top Overlay	GENERATED : 12/25/2015 15:35:45	TEXAS INSTRUMENTS	



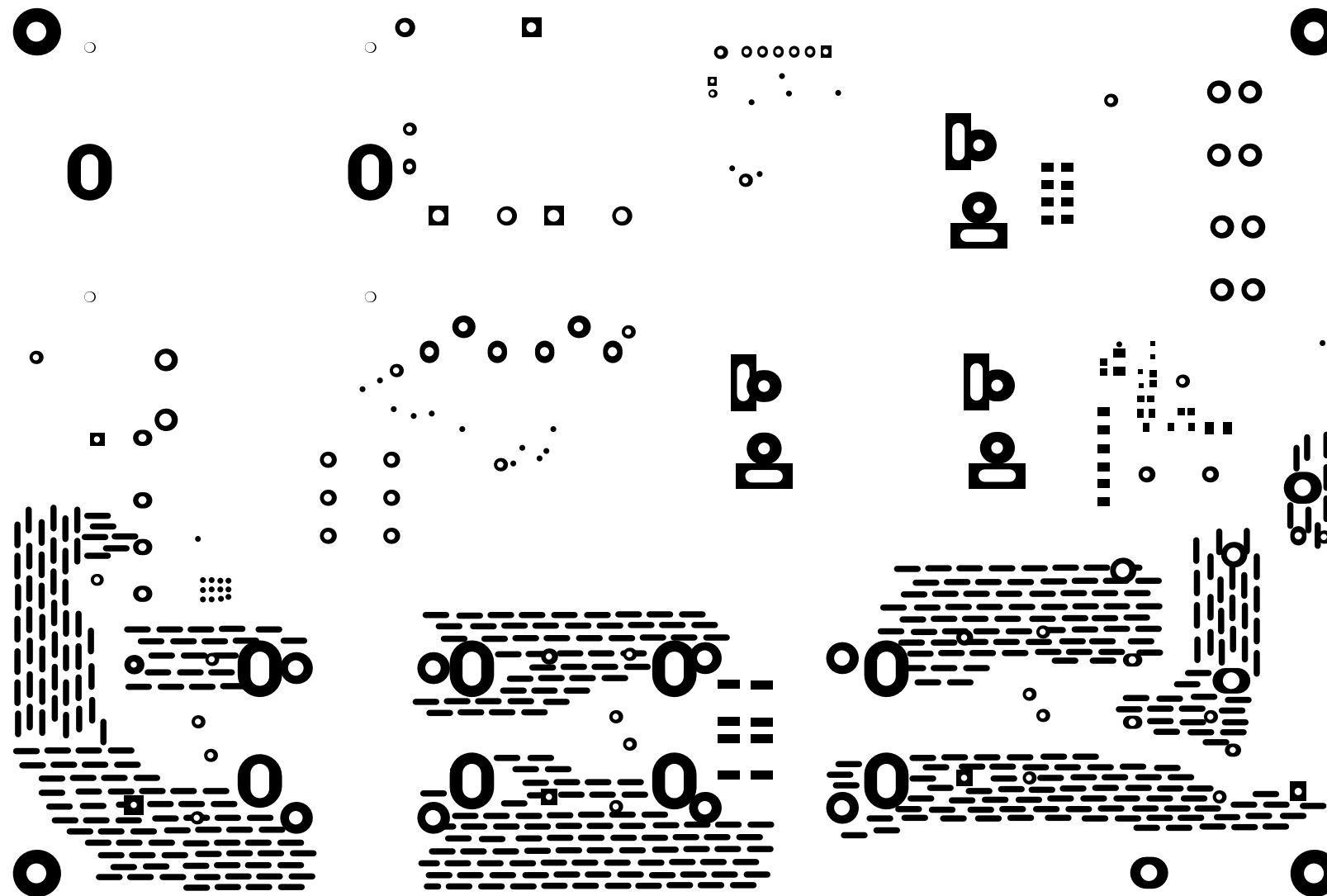
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Top Solder Mask	GENERATED : 12/25/2015 15:35:46		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Top Layer	GENERATED : 12/25/2015 15:35:47	TEXAS INSTRUMENTS	

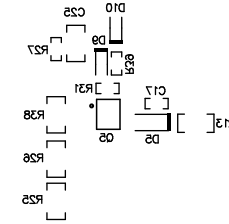
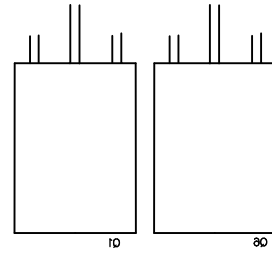
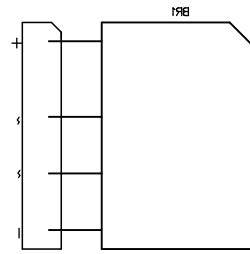
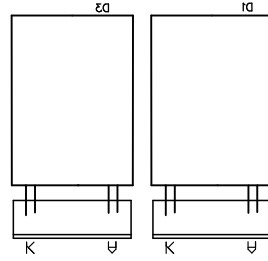


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Bottom Layer	GENERATED : 12/25/2015 15:35:47		TEXAS INSTRUMENTS

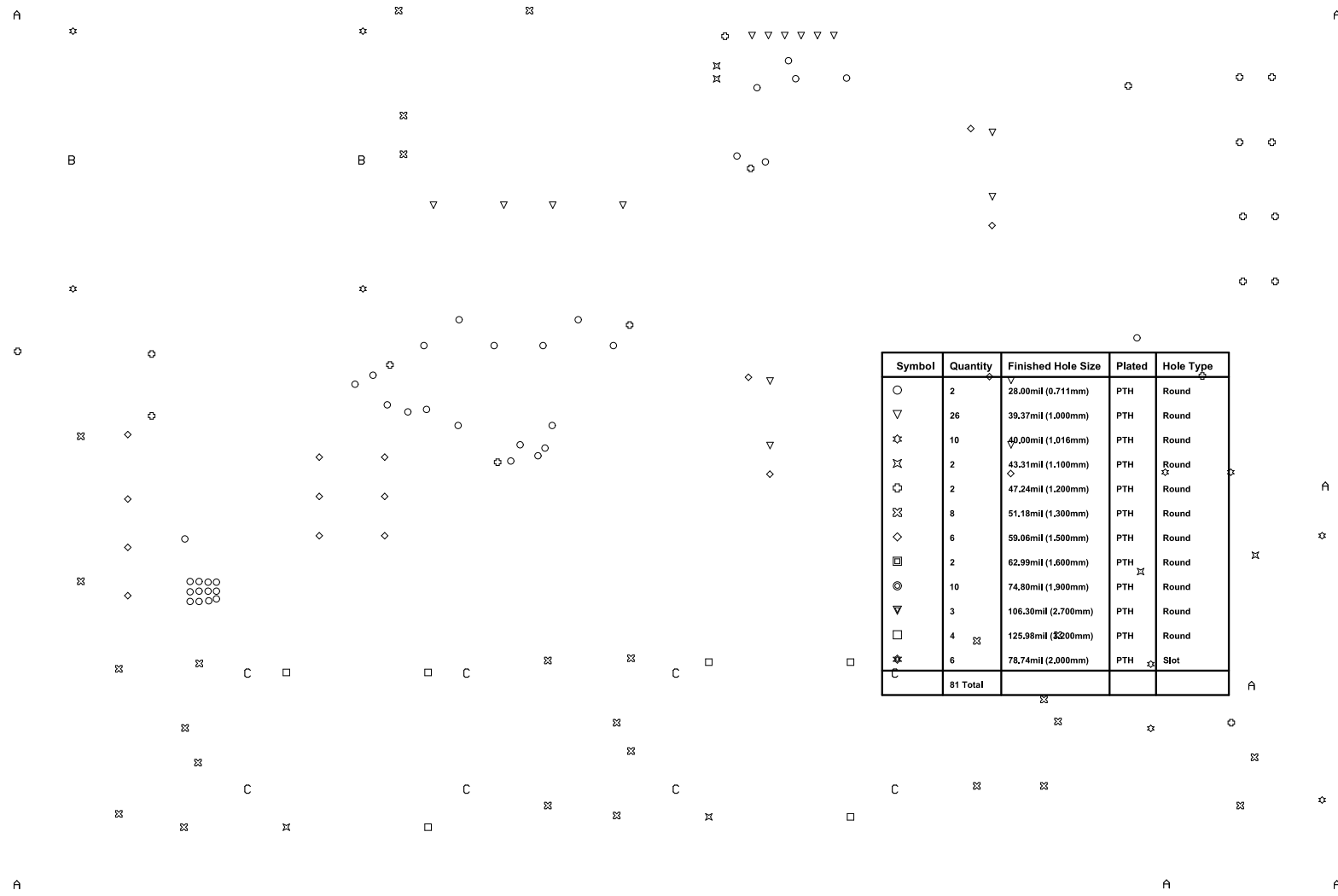


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/25/2015 15:35:48	TEXAS INSTRUMENTS	

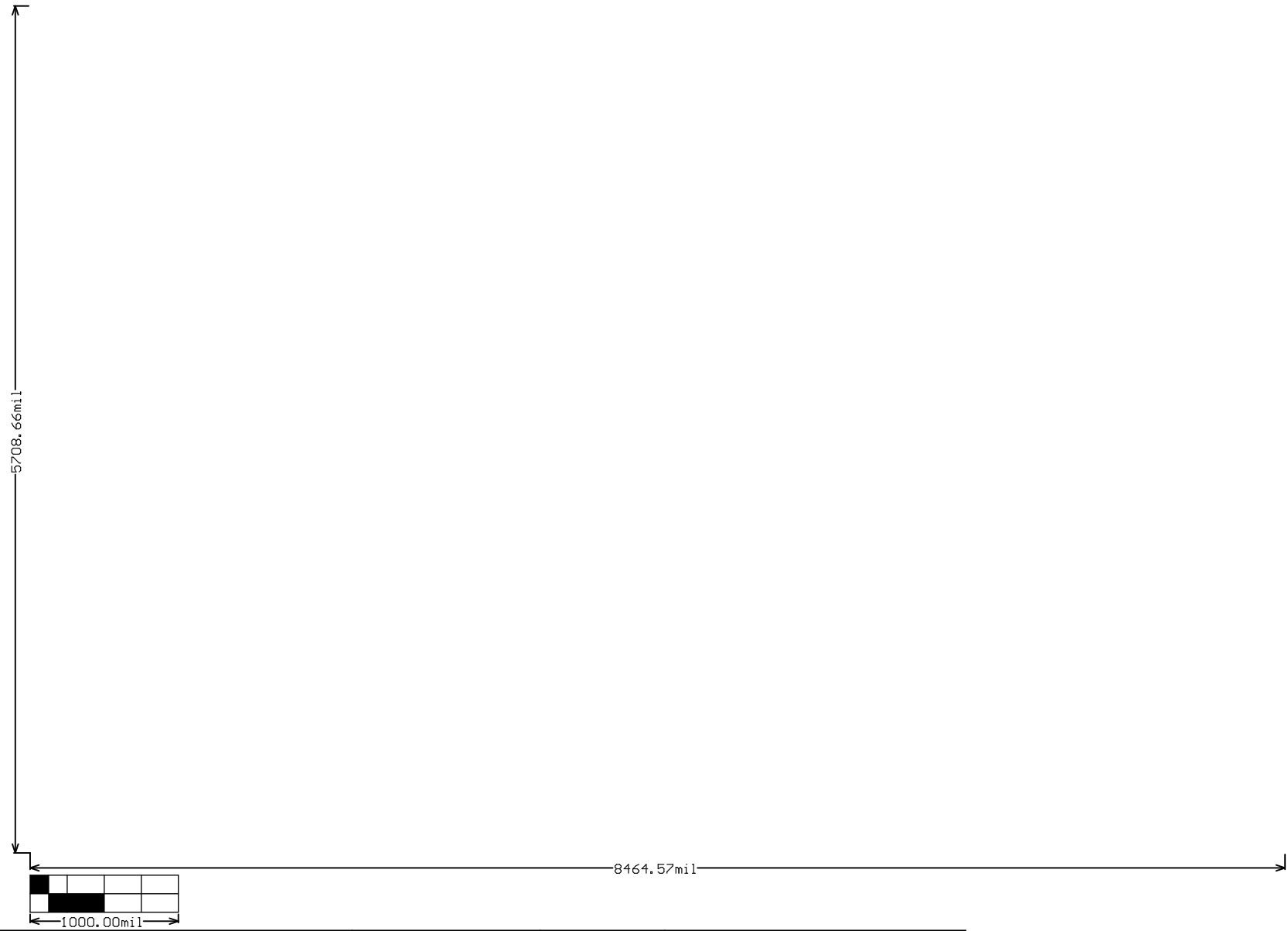
TIDA-00779 Rev B



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00779		
PLOT NAME = Bottom Overlay	GENERATED : 12/25/2015 15:35:49		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00779		
PLOT NAME = Drill Drawing	GENERATED : 12/25/2015 15:35:49	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00779	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00779		
PLOT NAME = Board Dimensions	GENERATED : 12/25/2015 15:35:50	TEXAS INSTRUMENTS	



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